



6 Channel EMI Filter Array with ESD Protection

CM1400-03

Features

- Functionally and pin compatible with CSPEMI306A device
- OptiGuard[™] coated for improved reliability at assembly
- Six channels of EMI filtering for data ports
- Pi-style EMI filters in a capacitor-resistorcapacitor (C-R-C) network
- 40dB absolute attenuation (typical) at 1 GHz
- 35dB attenuation (typical) at 1 GHz relative to pass band
- ±15kV ESD protection on each channel (IEC 61000-4-2 Level 4, contact discharge)
- ±30kV ESD protection on each channel (HBM)
- 15-bump, 2.960mm X 1.330mm footprint Chip Scale Package (CSP)
- Chip Scale Package features extremely low lead inductance for optimum filter and ESD performance
- RoHS compliant (lead-free) finishing

Applications

- EMI filtering and ESD protection for both data and I/O ports
- Wireless Handsets
- Handheld PCs / PDAs
- MP3 Players
- Notebooks
- Desktop PCs

Product Description

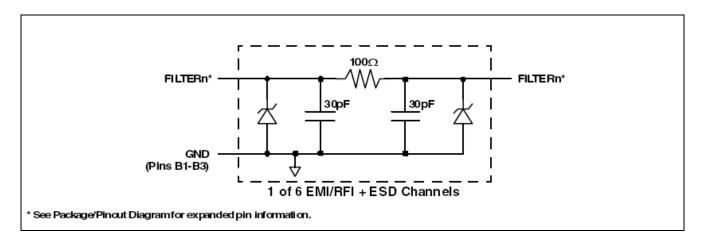
The CM1400-03 is a six channel low-pass filter array that reduces EMI/RFI emissions while at the same time providing ESD protection. It is used on data ports on mobile devices. To reduce EMI/RFI emissions, the CM1400-03 integrates a pi-style filter (C-R-C) for each of the 6 channels. Each high quality filter provides greater than 30dB attenuation in the 800-2700 MHz range relative to the pass band attenuation. These pi-style filters also support bidirectional filtering, controlling EMI both to and from a data port connector.

In addition, the CM1400-03 provides a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The input pins are designed and characterized to safely dissipate ESD strikes of ± 15 kV, exceeding the maximum requirement of the IEC 61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the device provides protection for contact discharges to greater than ± 30 kV.

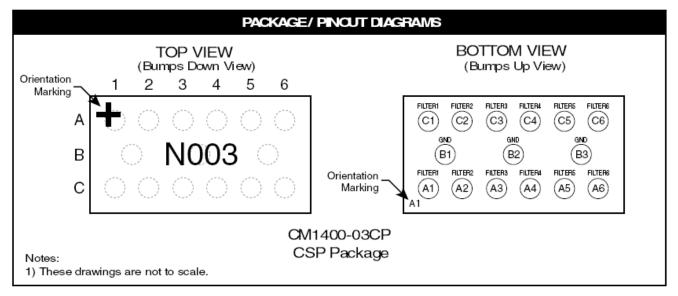
The CM1400-03 is particularly well suited for portable electronics (e.g., cellular telephones, PDAs, notebook computers) because of its small package footprint and low weight.

The CM1400-03 incorporates *OptiGuard*[™] coating which results in improved reliability at assembly. The CM1400-03 is available in a space-saving, low-profile chip scale package with RoHS compliant lead-free finishing.

Block Diagram



Package/Pinout Diagrams



| | PIN DESCRIPTIONS | | | | |
|--------|------------------|------------------|--|--|--|
| PIN(s) | NAME | DESCRIPTION | | | |
| A1 | FILTER1 | Filter Channel 1 | | | |
| A2 | FILTER2 | Filter Channel 2 | | | |
| A3 | FILTER3 | Filter Channel 3 | | | |
| A4 | FILTER4 | Filter Channel 4 | | | |
| A5 | FILTER5 | Filter Channel 5 | | | |
| A6 | FILTER6 | Filter Channel 6 | | | |
| B1-B3 | GND | Device Ground | | | |
| C1 | FILTER1 | Filter Channel 1 | | | |
| C2 | FILTER2 | Filter Channel 2 | | | |
| C3 | FILTER3 | Filter Channel 3 | | | |
| C4 | FILTER4 | Filter Channel 4 | | | |
| C5 | FILTER5 | Filter Channel 5 | | | |
| C6 | FILTER6 | Filter Channel 6 | | | |

Ordering Information

| PART NUMBERING INFORMATION | | | | | | | |
|----------------------------|---------|-----------------------------------|--------------|--|--|--|--|
| Bumps | Package | Ordering Part Number ¹ | Part Marking | | | | |
| 15 | CSP | CM1400-03CP | N003 | | | | |

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

Specifications

| ABSOLUTE MAXIMUM RATINGS | | | | | |
|---------------------------|-------------|-------|--|--|--|
| PARAMETER | RATING | UNITS | | | |
| Storage Temperature Range | -65 to +150 | °C | | | |
| DC Power per Resistor | 100 | mW | | | |
| DC Package Power Rating | 600 | mW | | | |

| STANDARD OPERATING CONDITIONS | | | | | |
|-------------------------------|------------|-------|--|--|--|
| PARAMETER | RATING | UNITS | | | |
| Operating Temperature Range | -40 to +85 | °C | | | |

| | ELECTRICAL OPERATING CHARACTERISTICS (SEE NOTE1) | | | | | |
|-------------------|--|--------------------------|-------------|-------------|-------------|----------|
| SYMBOL | PARAMETER | CONDITIONS | MIN | ТҮР | МАХ | UNITS |
| R | Resistance | | 80 | 100 | 120 | Ω |
| С | Capacitance | At 2.5V DC | 24 | 30 | 36 | pF |
| TCR | Temperature Coefficient of Resistance | | | 1200 | | ppm/°C |
| тсс | Temperature Coefficient of Capacitance | At 2.5V DC | | -300 | | ppm/°C |
| V | Diode Voltage (reverse bias) | I _{DIODE} =10μA | | 6.0 | | V |
| I _{leak} | Diode Leakage Current (reverse bias) | V _{DIODE} =3.3V | | | 100 | nA |
| V _{SIG} | Signal Voltage Positive Clamp Negative Clamp | I _{LOAD} = 10mA | 5.6 -1.5 | 6.8 -0.8 | 9.0 -0.4 | v v |
| V _{ESD} | In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4 | Note 2 | ±30 ±15 | | | kV kV |
| V _{CL} | Clamping Voltage during ESD Discharge MIL-STD-883 (Method 3015), 8kV Positive Transients Negative Transients | Notes 2 and 3 | | +10 -5 | | V V |
| f _c | Cut-off Frequency $Z_{SOURCE} = 50\Omega, Z_{LOAD} = 50\Omega$ | R=100Ω, C=30pF | | 58 | | MHz |

Note 1: T_A=25°C unless otherwise specified. Note 2: ESD applied to input and output pins with respect to GND, one at a time. Note 3: Clamping voltage is measured at the opposite side of the EMI filter to the ESD pin. For example, if ESD is applied to Pin A1, then clamping voltage is measured at Pin C1.

Performance Information

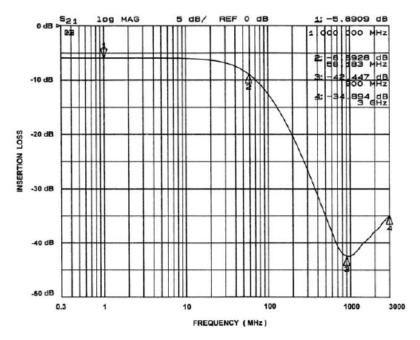


Figure 1. Insertion Loss vs. Frequency (A1-C1 to GND B2)

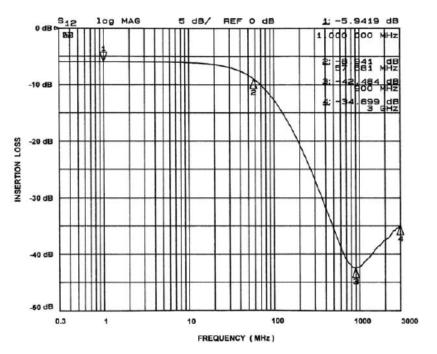


Figure 2. Insertion Loss vs. Frequency (A2-C2 to GND B2)

Performance Information (cont'd)

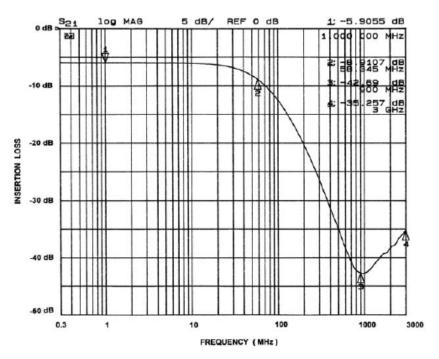


Figure 3. Insertion Loss vs. Frequency (A3-C3 to GND B2)

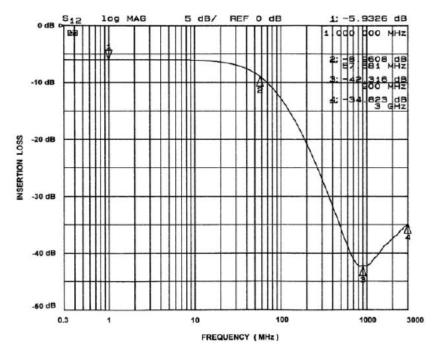


Figure 4. Insertion Loss vs. Frequency (A4-C4 to GND B2)

Performance Information (cont'd)

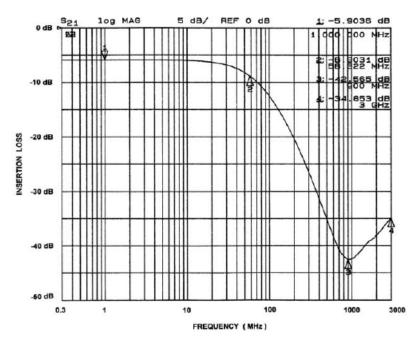


Figure 5. Insertion Loss vs. Frequency (A5-C5 to GND B2)

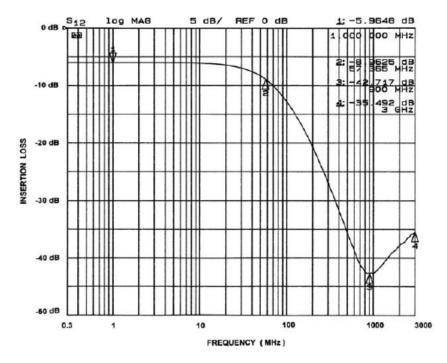


Figure 6. Insertion Loss vs. Frequency (A6-C6 to GND B2)

Performance Information (cont'd)

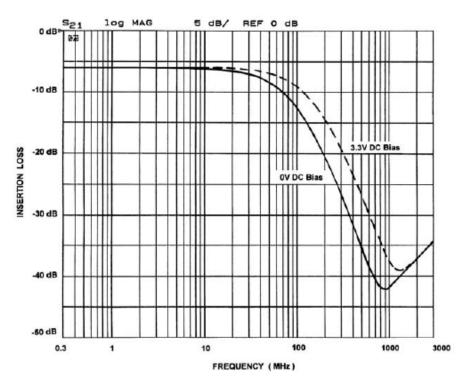
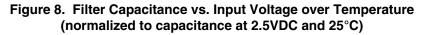
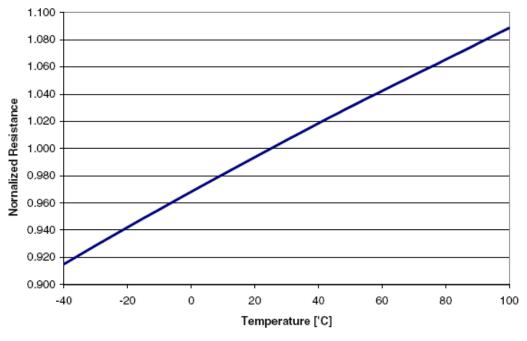


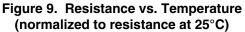
Figure 7. Comparison of Filter Response Curves for CM1400-03 with DC Bias

1.6 1.5 1.4 Normalized Capacitance 1.3 1.2 -----T = -40C T = +25C 1.1 — T = +70C 1.0 0.9 0.8 0.7 0 1 2 з 4 5 DC Input Voltage (V)

Performance Information (cont'd)

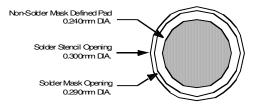






Application Information

| PARAMETER | VALUE |
|--|------------------------------|
| Pad Size on PCB | 0.240mm |
| Pad Shape | Round |
| Pad Definition | Non-Solder Mask defined pads |
| Solder Mask Opening | 0.290mm Round |
| Solder Stencil Thickness | 0.125mm - 0.150mm |
| Solder Stencil Aperture Opening (laser cut, 5% tapered walls) | 0.300mm Round |
| Solder Flux Ratio | 50/50 by volume |
| Solder Paste Type | No Clean |
| Pad Protective Finish | OSP (Entek Cu Plus 106A) |
| Tolerance — Edge To Corner Ball | <u>+</u> 50μm |
| Solder Ball Side Coplanarity | <u>+</u> 20μm |
| Maximum Dwell Time Above Liquidous | 60 seconds |
| Maximum Soldering Temperature for Lead-free Devices using a Lead-free Solder Paste | 260°C |





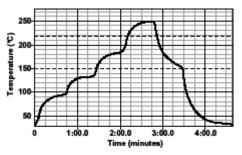


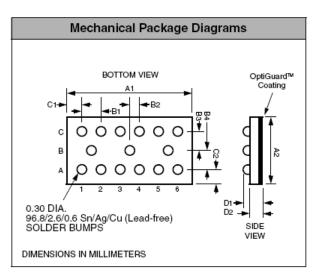
Figure 9. Lead-free (SnAgCu) Solder Ball Reflow Profile

Mechanical Details

CSP Mechanical Specifications

The CM1400-03 is supplied in a custom Chip Scale Package (CSP). Dimensions are presented below.

| | PACKAGE DIMENSIONS | | | | | | |
|------|------------------------------------|-------------|-------|--------|--------|--------|--|
| Pack | age | Custom CSP | | | | | |
| Bun | nps | 15 | | | | | |
| Dim | м | lillimeters | | | Inches | | |
| Dim | Min | Nom | Max | Min | Nom | Max | |
| A1 | 2.915 | 2.960 | 3.005 | 0.1148 | 0.1165 | 0.1183 | |
| A2 | 1.285 | 1.330 | 1.375 | 0.0506 | 0.0524 | 0.0541 | |
| B1 | 0.495 | 0.500 | 0.505 | 0.0195 | 0.0197 | 0.0199 | |
| B2 | 0.245 | 0.250 | 0.255 | 0.0096 | 0.0098 | 0.0100 | |
| B3 | 0.430 | 0.435 | 0.440 | 0.0169 | 0.0171 | 0.0173 | |
| B4 | 0.430 | 0.435 | 0.440 | 0.0169 | 0.0171 | 0.0173 | |
| C1 | 0.180 | 0.230 | 0.280 | 0.0071 | 0.0091 | 0.0110 | |
| C2 | 0.180 | 0.230 | 0.280 | 0.0071 | 0.0091 | 0.0110 | |
| D1 | 0.575 | 0.644 | 0.714 | 0.0226 | 0.0254 | 0.0281 | |
| D2 | 0.368 | 0.419 | 0.470 | 0.0145 | 0.0165 | 0.0185 | |
| | # per tape and 3500 pieces reel | | | | | | |
| | Controlling dimension: millimeters | | | | | | |



Package Dimensions for CM1400-03 Chip Scale Package

CSP Tape and Reel Specifications

| PART NUMBER | CHIP SIZE (mm) | POCKET SIZE (mm) B _o X A _o X K _o | TAPE WIDTH W | REEL DIAMETER | QTY PER REEL | P₀ | P ₁ |
|-------------|---------------------|--|-----------------|------------------|-----------------|-----|----------------|
| CM1400-03 | 2.96 X 1.33 X 0.644 | 3.10 X 1.45 X 0.74 | 8mm | 178mm (7") | 3500 | 4mm | 4mm |

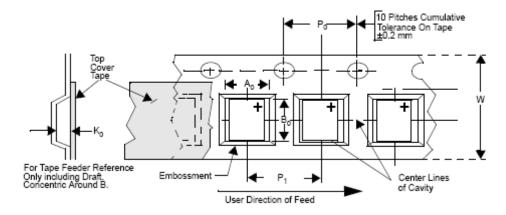


Figure 12. Tape and Reel Mechanical Data

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other application in which the failure of the SCILLC product create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Emal I: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5773-3850 ON Semi conductor Websi te: www.onsemi.com

Order Li terature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative